

# HVM14

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

# HITACHI

ADE-208-082C (Z)

Rev. 3

May 1993

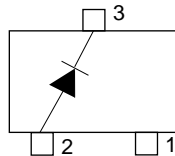
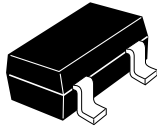
## Features

- Low forward resistance. ( $r_f = 7.0$  max)
- Low capacitance. ( $C = 0.25$ pFtyp)
- MPAK package is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HVM14	H5	MPAK

## Pin Arrangement



(Top View)

- 1 NC
- 2 Anode
- 3 Cathode

## Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	50	V
Forward current	$I_F$	50	mA
Power dissipation	$P_d$	100	mW
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

## Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	—	1.0	V	$I_F = 50\text{mA}$
Reverse current	$I_R$	—	—	100	nA	$V_R = 50\text{V}$
Capacitance	$C$	—	0.25	—	pF	$V_R = 50\text{V}$ , $f = 1\text{MHz}$
Forward resistance	$r_f$	—	—	7.0	$\Omega$	$I_F = 10\text{mA}$ , $f = 100\text{MHz}$
ESD-Capability	—	200	—	—	V	*C = 200pF, Both forward and reverse direction 1 pulse.

Note: Failure criterion;  $I_R \geq 200\text{nA}$  at  $V_R = 50\text{V}$

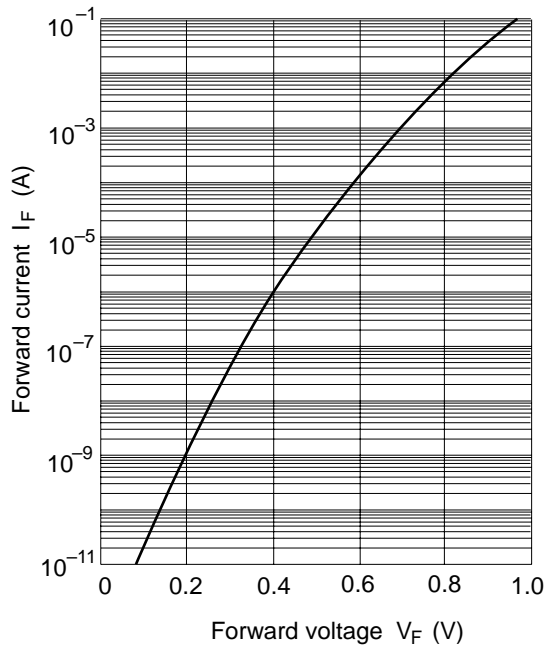
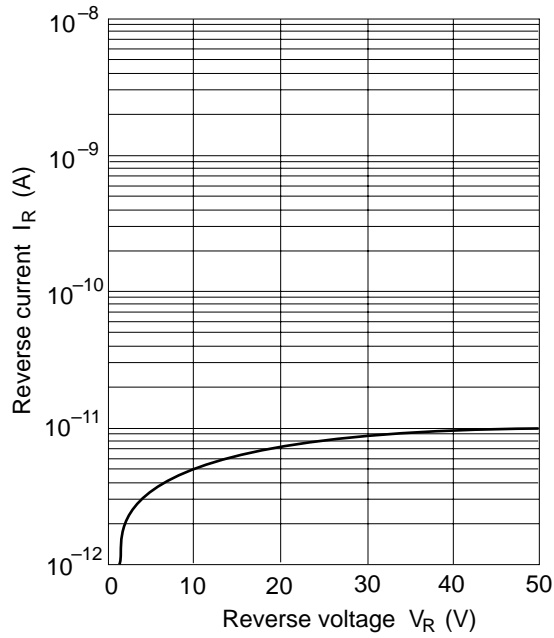
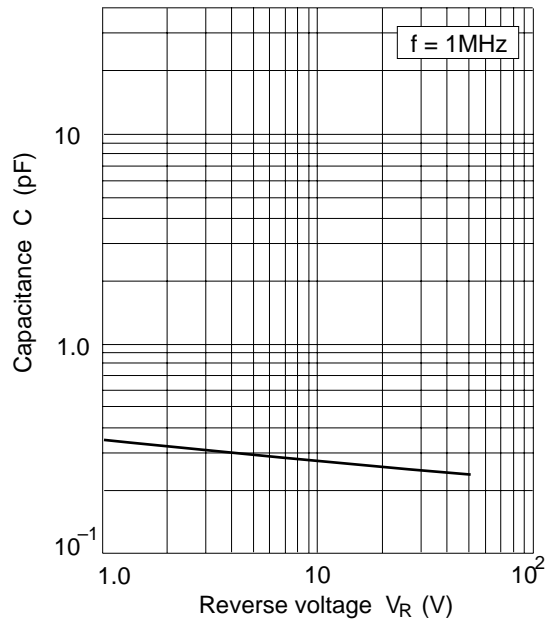


Fig.1 Forward current Vs. Forward voltage



**Fig.2 Reverse current Vs. Reverse voltage**



**Fig.3 Capacitance Vs. Reverse voltage**

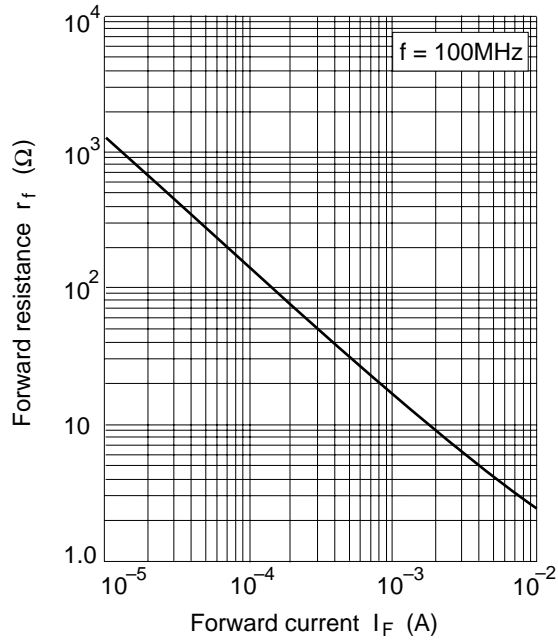
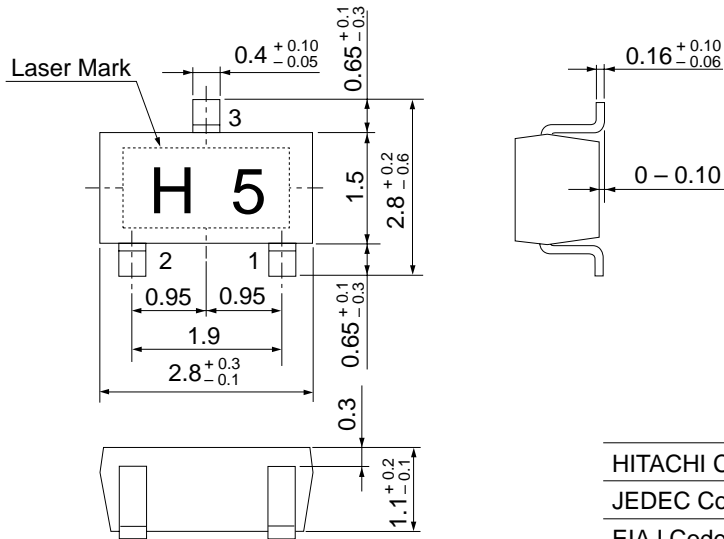


Fig.4 Forward resistance Vs. Forward current

Package Dimensions

Unit: mm



- 1 NC
- 2 Anode
- 3 Cathode

HITACHI Code	MPAK(1)
JEDEC Code	—
EIAJ Code	SC-59A
Weight (g)	0.011

## Cautions

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